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To;

SPECIFICATIONS

Product Type 80 Output LCD Segment Driver

Model No	ο.	L H 1 5 1 4 A F

*This tentative specifications contains 20 pages including the cover and appendix.

If you have any objections, please contact us before issuing purchasing order.

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[Note]

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1. Summary

The LH1514AF is a 80 output segment driver LSI suitable for driving black and white dot matrix LC panels.

Through the use of SST (Super Slim TCP) technology, it is ideal for substantially decreasing the size of the frame section of the LC module. The LH1514AF is particularly well suited to driving black and white LC panels used for palmtop personal computers because of its low-voltage operation (Supply voltage for logic system: -5.5 to -2.5 V).

When combined with the LH1513A Common Driver, a low power consuming, high-precision LC panel display can be assembled.

2. Features

• Supply voltage for the logic system : -5.5 to -2.5 V

• Supply voltage for LC drive : -28.0 to -10.0 V

(absolute maximum rating -30.0 V)

• Number of LC drive outputs : 80

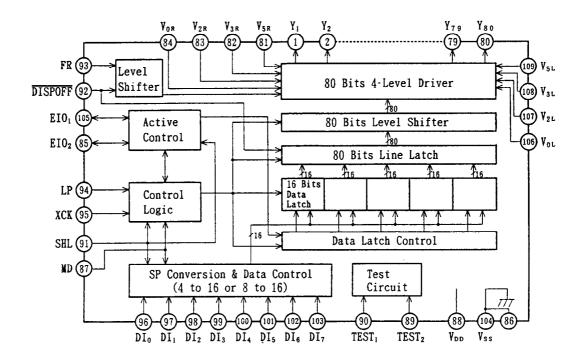
• Low output impedance : 1.5 k Ω (Typ.) • Shift Clock frequency : 6.5 MHz (Max.)

· Low power consumption

· Adopts a data bus system

- 4-bit/8-bit parallel input modes are selectable with a mode (MD) pin
- · Automatic transfer function of an enable signal
- Automatic counting function which, in the chip select mode, causes the internal clock to be stopped by automatically counting 80 of input data
- · Line latch circuit reset function when DISPOFF active
- Supports high capacity LC panel display when combined with the LH1513A Common Driver
- CMOS process (N-type Silicon Substrate)
- Package : 109 pin TCP (Tape Carrier Package)
- · Not designed or rated as radiation hardened

3. Block Diagram

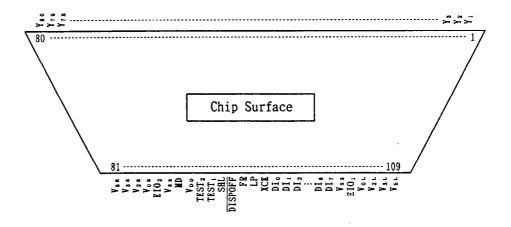


4. Functional Operations of Each Block

Block	Function
Active Control	Controls the selection or deselection of the chip.
	Following a LP signal input, and after the chip select signal is
	input, a select signal is generated internally until 80 bits of
	data have been read in.
	Once data input has been completed, a select signal for cascade
	connection is output, and the chip is deselected.
SP Conversion	Keep input data which are 4 clocks of XCK at 4-bit parallel mode
& Data Control	into latch circuit,or keep input data which are 2 clocks of XCK
	at 8-bit parallel mode into latch circuit, after that they are put
	on the internal data bus 16 bits at a time.
Data Latch	Selects the state of the data latch which reads in the data bus
Control	signals. The shift direction is controlled by the control logic,
	for every 16 bits of data read in, the selection signal shifts
	one bit based on the state of the control circuit.
Data Latch	Latches the data on the data bus. The latched state of each LC
	driver output pin is controlled by the control logic and the data
	latch control, 80 bits of data are read in five sets of 16 bits.
Line Latch	All 80 bits which have been read into the data latch are
	simultaneously latched on the falling edge of the LP signal, and
	output to the level shifter block.

Block	Function
Level Shifter	The logic voltage signal is level-shifted to the LC drive voltage
	level, and output to the driver block.
4-Level Driver	Drives the LC driver output pins from the latch data, selecting
	one of 4 levels (V_0, V_2, V_3, V_5) based on the FR and DISPOFF
	signals.
Control Logic	Controls the operation of each block. When a LP signal has been
	input, all blocks are reset and the control logic waits for the
	selection signal output from the active control block.
	Once the selection signal has been output, operation of the data
	latch and data transmission are controlled, 80 bits of data are
	read in, and the chip is deselected.

5. Pin Configuration



LH1514AF

6. Pin Descriptions

6-1. Pin Designations

Pin No.	Symbol	I/0	Designation
1 to 80	Y ₁ -Y ₈₀	0	LC drive output
81, 109	V _{5R} ,V _{5L}	-	Power supply for LC drive
82, 108	V _{3R} ,V _{3L}	-	Power supply for LC drive
83, 107	V _{2R} ,V _{2L}		Power supply for LC drive
84, 106	V _{OR} ,V _{OL}	-	Power supply for LC drive
85, 105	EIO2, EIO1	I/0	Input/Output for chip select
86, 104	V _{ss}	-	Ground (0 V)
87	MD	I	Mode selection input
88	V _{D D}		Power supply for logic system (-5.5 to -2.5 V)
89	TEST ₂	I	Test mode selection input
90	TEST ₁	I	Test mode selection input
91	SHL	I	Display data shift direction selection
92	DISPOFF	I	Control input for deselect output level
93	FR	I	AC-converting signal input for LC drive waveform
94	LP	I	Display data latch pulse input
95	XCK	I	Display data shift clock input
96 to 103	DI ₀ -DI ₇	I	Display data input

6-2. Input/Output Circuits

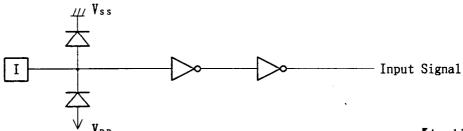


Fig.1 Input Circuit

[Applicable pins]
DI₀₋₇,XCK,LP,FR
SHL,MD,DISPOFF

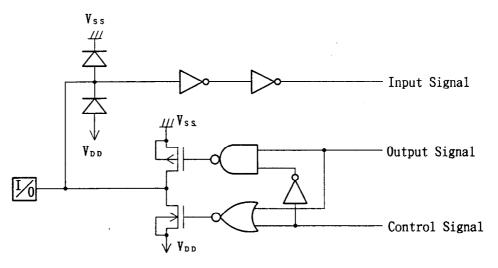


Fig. 2 Input/Output Circuit

[Applicable pins] EIO₁,EIO₂

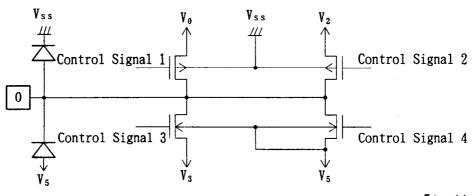


Fig.3 LC Drive Output Circuit

[Applicable pins] $Y_1 - Y_{80}$

7. Description of Functional Operations

7-1. Pin Functions

Symbol	Function
V _{DD}	Logic system power supply pin connects to -5.5 to -2.5 V
Vss	Ground pin connects to 0 V
V _{OR} , V _{OL}	Power supply pin for LC driver voltage bias.
V _{2R} ,V _{2L}	•Normally, the bias voltage used is set by a resistor divider.
V _{3R} ,V _{3L}	•Ensure that voltages are set such that $V_{ss} \ge V_0 > V_2 > V_3 > V_5$.
V _{5R} , V _{5L}	•To further reduce the difference between the output waveforms of LC
	driver output pins Y_1 and Y_{80} , externally connect V_{1R} and V_{1L}
	(i=0, 2, 3, 5).
DI ₀ -DI ₇	Input Pin for display data
	•In 4-bit parallel input mode, input data into the 4 pins DI_0 - DI_3 .
Í	Connect DI_4 - DI_7 to V_{ss} or V_{DD} .
	•In 8-bit parallel input mode, input data into the 8 pins DI_0 - DI_7 .
XCK	Clock input pin for taking display data
	•Data is read on the falling edge of the clock pulse.
LP	Latch pulse input pin for display data
	·Data is latched on the falling edge of the clock pulse.
SHL	Direction selection pin for reading display data
	•When set to V_{DD} level "L", data is read sequentially from $Y_{8\theta}$ to Y_1 .
	•When set to V_{ss} level "H", data is read sequentially from Y_1 to Y_{80} .
DISPOFF	Control input pin for output deselect level
	•The input signal is level-shifted from logic voltage level to LC
	drive voltage level, and controls LC drive circuit.
	•When set to V_{DD} level "L", the LC drive output pins $(Y_1-Y_{8.0})$ are set
	to level V ₀ .
	•While set to "L", the contents of the line latch are reset, but read
	the display data in the data latch regardless of condition of
	DISPOFF. When the DISPOFF function is canceled, the driver outputs
	deselect level $(V_2 \text{ or } V_3)$, then outputs the contents of the date
	latch on the next falling edge of the LP. That time, if DISPOFF
]	removal time can not keep regulation what is shown AC
	characteristics(Page 14), can not output the reading data correctly.
FR	AC signal input for LC driving waveform
[•The input signal is level-shifted from logic voltage level to LC
	drive voltage level, and controls LC drive circuit.
	• Normally, inputs a frame inversion signal.
	•The LC driver output pin's output voltage level can be set using
	the line latch output signal and the FR signal. Table of truth values
L	is shown in 7-2-1.



Symbol	Function
MD EIO ₁	Mode selection pin \cdot When set to V_{DD} level "L", 4-bit parallel input mode is set. \cdot When set to V_{SS} level "H", 8-bit parallel input mode is set. \cdot The relationship between the display data and driver output pins is shown in 7-2-2. Input/Output pin for chip selection
EIO ₂	•When SHL input is at V_{DD} level "L". EIO_1 is set for output, and EIO_2 is set for input. •When SHL input is at V_{SS} level "H", EIO_1 is set for input, and EIO_2 is set for output. •During output, set to "H" while $LP^*\overline{XCK}$ is "H" and after 80 bits of data have been read set to "L" for one cycle (from falling edge to falling edge of the XCK), after which it return to "H". •During input, after the LP signal is input, the chip is selected while EI is set to "L". After 80-bits of data have been read, the chip is deselected.
TEST ₁	Test mode select pin
TEST ₂	•During normal operation. tie to V_{DD} level "L".
Y ₁ -Y ₈₀	LC driver output pins •Corresponding directly to each bit of the data latch, one level $(V_0,\ V_2,\ V_3,\ or\ V_5)$ is selected and output.

7-2. Functional Operations

7-2-1. Truth Table

FR	Latch Data		Driver Output Voltage Level (Y ₁ -Y ₈₀)
L	L	Н	V ₂
L	Н	Н	V _o
Н	L	Н	V ₃
Н	Н	Н	V ₅
X	X	L	V ₀

Here, $V_{ss} \ge V_0 > V_2 > V_3 > V_5$, L: V_{DD} (-5.5 to -2.5 V), H: V_{ss} (0 V), x: Don't care

[Note] "Don't care" should be fixed to "H" or "L", avoiding floating.

There are two kinds of power supply (logic level voltage,LC drive voltage) for LCD driver, please supply regular voltage which assigned by specification for each power pin.

7-2-2. Relationship between the Display Data and Driver Output pins

(a) 4-Bit Parallel Mode

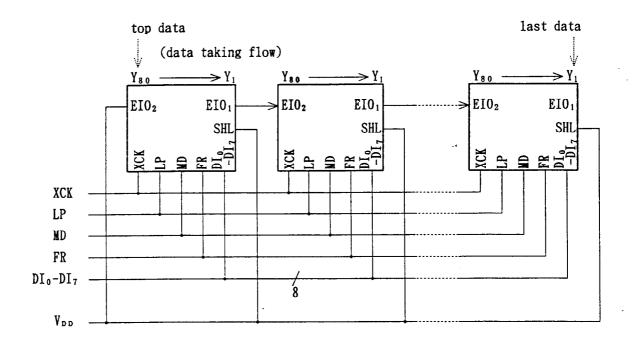
MD	SHL	EIO ₁	EIO ₂	Data		Figure of Clock					
				Input	20clock	19clock	18clock	•••	3clock	2clock	lclock
				DIo	Υ 1	Y 5	Υ 9	•••	Y 6 9	Y 7 3	Y 7 7
1				DI 1	Y 2	Υ 6	Y 1 0	•••	Y 7 0	Y 7 4	Y ₇₈
L	L	Output	Input	DI ₂	Y 3	Y 7	Y ₁₁	•••	Y ₇₁	Y 7 5	Y 7 9
<u></u>				DΙ ₃	Y 4	Υ 8	Y ₁₂	•••	Y 7 2	Y 7 8	Y 8 0
				DΙο	Y ₈₀	Y 7 6	Y ₇₂	•••	Y ₁₂	Y 8	Y 4
				DIı	Y ₇₉	Y ₇₅	Y ₇₁	•••	Y ₁₁	Y 7	Y 3
L	Н	Input	Output	DI ₂	Y ₇₈	Y 7 4	Y 7 0	•••	Y ₁₀	Y ₆	Υ 2
<u> </u>				DI ₃	Y ₇₇	Y ₇₃	Y 6 9	•••	Y 9	Y 5	Υ 1

(b) 8-Bit Parallel Mode

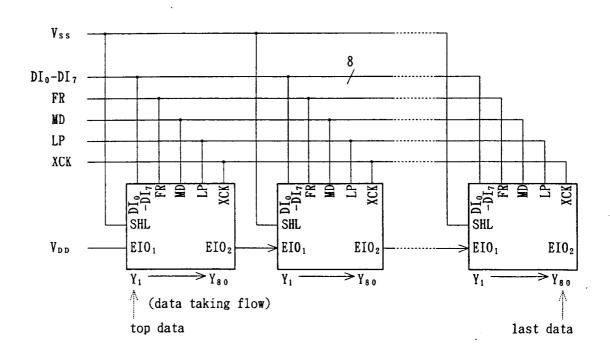
MD	SHL	EIO ₁	EIO ₂	Data	Data Figure of Clock						
				Input	20clock	19clock	18clock	•••	3clock	2clock	1clock
				DΙο	Y 1	Y 9	Y ₁₇	•••	Y ₅₇	Y 6 5	Y ₇₃
				DI ₁	Y · 2	Υ ₁₀	Y ₁₈	•••	Y 5 8	Y _{вв}	Y 7 4
	}			DI ₂	Y 3	Y ₁₁	Y 1 9	•••	Y ₅₉	Y ₆₇	Y ₇₅
				DI ₃	Y 4	Y ₁₂	Y 2 0	•••	Y 6 0	Y 68	Y 7 6
Н	L	Output	Input	DI ₄	Y 5	Y ₁₃	Y ₂₁	•••	Y ₆₁	Y 6 9	Y 7 7
1				DI ₅	Υ 6	Y ₁₄	Y 2 2	•••	Y ₆₂	Y 7 0	Y ₇₈
				DI ₆	Υ 7	Y ₁₅	Y 2 3	•••	Y 6 3	Y 7 1	Y ₇₉
				DI ₇	Y 8	Y ₁₆	Y 2 4	•••	Y 6 4	Y 7 2	Y ₈₀
				DIo	Y ₈₀	Y ₇₂	Y ₆₄		Y ₂₄	Y 16	Y 8
				DIı	Y 7 9	Y ₇₁	Y 6 3	•••	Y ₂₃	Y 1 5	Υ 7
				DI2	Y ₇₈	Y ₇₀	Y ₆₂	•••	Y 2 2	Y ₁₄	Υ 6
				DI ₃	Y 7 7	Y 6 9	Y ₆₁	•••	Y ₂₁	Y 1 3	Υ 5
Н	Н	Input	Output	DI ₄	Y 7 6	Y ₆₈	Y ₆₀	•••	Y 2 0	Y 1 2	Υ 4
				DIs	Y 7 5	Y ₆₇	Y 5 9	•••	Y 1 9	Υ ₁₁	Y 3
				DI6	Y ₇₄	Y 6 6	Y ₅₈	•••	Y 1 8	Y ₁₀	Y 2
				DI ₇	Y ₇₃	Y ₆₅	Y ₅₇	•••	Y ₁₇	Y 9	Y 1

7-2-3. Connection Examples of Plural Segment Drivers

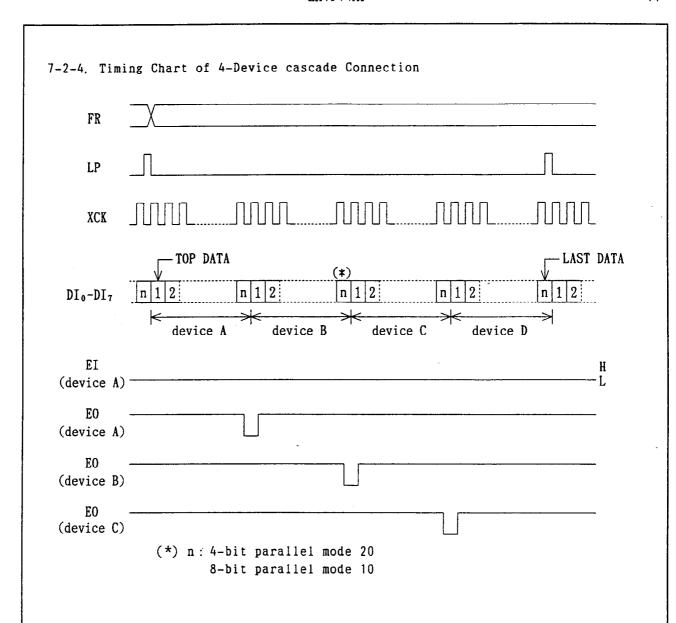
(a) Case of SHL="L"



(b) Case of SHL="H"







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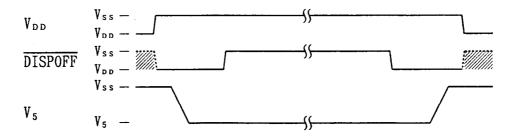


8. Precaution

- OPrecaution when connecting or disconnecting the power
 This LSI has a high-voltage LCD driver, so it may be permanently damaged by
 a high current which may flow if a voltage is supplied to the LC drive
 power supply while the logic system power supply is floating.
 The detail is as follows.
 - •When connecting the power supply, connect the LC drive power after connecting the logic system power. Furthermore, when disconnecting the power, disconnect the logic system power after disconnecting the LC drive power.
 - •We recommend you connecting the serial resistor (50 to 100 Ω) to the LC drive power V_5 of the system as a current limitter resistor. And set up the suitable value of the resistor in consideration of LC display grade.

And when connecting the logic power supply, the logic condition of this LSI inside is insecurity. Therefore connecting the LC drive power supply after resetting logic condition of this LSI inside on $\overline{\text{DISPOFF}}$ function. After that, cancel the $\overline{\text{DISPOFF}}$ function after the LC drive power supply has become stable. Furthermore, when disconnecting the power, set the LC driver output pins to level V_0 on $\overline{\text{DISPOFF}}$ function. After that, disconnect the logic system power after disconnecting the LC drive power.

When connecting the power supply, show the following recommend sequence.





9. Absolute Maximum Ratings

Parameter	Symbo	Conditions	Applicable pins	Ratings	Unit
Supply voltage (1)	V _{D D}	Ta=25 ℃	V _{D D}	-7.0 to $+0.3$	V
Supply voltage (2)	V ₀	Referenced	V _{OL} , V _{OR}	$V_5 - 0.3$ to $+0.3$	γ
	V ₂	to $V_{ss}(0 \ V)$	V _{2L} , V _{2R}	$V_5 - 0.3$ to $+0.3$	V
	V ₃	1	V _{3L} , V _{3R}	$V_5 - 0.3$ to $+0.3$	V
	V ₅	1	V _{5L} ,V _{5R}	-30.0 to +0.3	V
Input voltage	۷,		DI ₀₋₇ , XCK, LP, SHL, FR	$V_{DD} = 0.3$ to $+0.3$	٧
			MD, EIO1, EIO2, DISPOFF		
Storage temperature	Tstg			-45 to +125	r

10. Recommended Operating Conditions

Parameter	Symbol	Conditions Appli	cable pins	Min.	Typ.	Max.	Unit
Supply voltage (1)	V _D D	Referenced V _{DD}		-5.5		-2.5	٧
Supply voltage (2)	V 5	to $V_{ss}(0 V)V_{5L},V_{5R}$		-28.0		-10.0	V
Operating temperature	Торг			-20		+85	r

11. Electrical Characteristics

11-1. DC Characteristics

 $(V_{SS}=V_0=0 \text{ V}, V_{DD}=-5.5 \text{ to } -2.5 \text{ V}, V_5=-28.0 \text{ to } -10.0 \text{ V}, Ta=-20 \text{ to } +85 \text{ }^{\circ})$

(155-10-0	, , , ,	<u>р</u> – 3.3 со	2.5 7, 75==20.0 00 =	10.0 ,	14-20	, , ,	0,
Parameter	Symbol	Conditions	Applicable pins	Min.	Typ.	Max.	Unit
Input voltage	V _{I Н}		DI ₀₋₇ ,XCK,LP,SHL,FR	0.2V _{DD}			٧
	V _{IL}		MD, EIO1, EIO2, DISPOFF			0.8V _{DD}	٧
Output voltage	V _{он}	$I_{OH} = -0.4$ mA	EIO ₁ ,EIO ₂	-0.4			γ
	VoL	$I_{oL}=+0.4$ mA				$V_{DD} + 0.4$	V
Input leakage current	ILI	$V_{SS} \ge V_1 \ge V_{DD}$	DI ₀₋₇ ,XCK,LP,SHL,FR			±10.0	μA
			MD, DISPOFF				
I/O leakage current	IL1/0	$V_{SS} \ge V_i \ge V_{DD}$	EIO ₁ ,EIO ₂			±10.0	μA
Output resistance	Ron	*1	Y 1 - Y 8 0		1.5	3.0	kΩ
Stand-by current	IstB	*2	Vss		-	50.0	μА
Consumed current (1)	IDDI	$V_{DD} = -3 \ V.*3$	V _D Q			0.6	πA
(Deselection)		$V_{DD} = -5 \ V,*3$				1.0	mA
Consumed current (2)	I _{DD2}	$V_{DD} = -3 \ V, *3$	۷ م م			3.0	πA
(Selection)		$V_{DD} = -5 \ V, *3$				5.0	πA
Consumed current (3)	I ₅	$V_{DD} = -3 \ V, *4$	V _{5L} ,V _{5R}			1.0	mΑ
		$V_{DD} = -5 \ V, *4$				1.0	mΑ

[Note]

- *1: $|\Delta V_{0N}| = 0.5 \text{ V}$
- *2: $V_{DD} = -5.0 \text{ V}$, $V_5 = -28.0 \text{ V}$, $V_{IH} = V_{SS}$, $V_{IL} = V_{DD}$, $TEST_1 = TEST_2 = V_{DD}$
- *3: $V_5 = -28.0 \text{ V}$, $f_{xck} = 6.15 \text{ MHz}$, No-load

The input data is turned over by data taking clock(4-bit parallel input mode)

*4: $V_5 = -28.0$ V, $f_{XCK} = 6.15$ MHz, $f_{LP} = 19.2$ kHz. $f_{FR} = 80$ Hz, No-load The input data is turned over by data taking clock(4-bit parallel input mode)

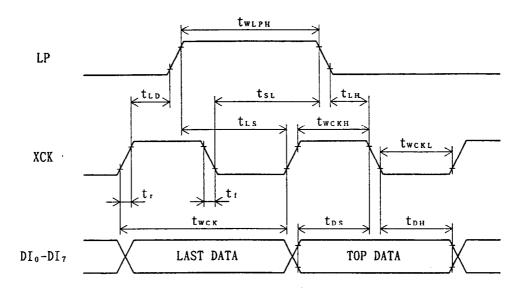
11-2. AC Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Shift clock period	twcĸ	t,,t,≦11 ns	152			ns
Shift clock "H" pulse width	twckn		65			ns
Shift clock "L" pulse width	twcki		65			ns
Data setup time	t _{DS}		50			ns
Data hold time	t _{вн}		40			ns
Latch pulse "H" pulse width	twiph		65			ns
Shift clock rise to Latch pulse rise time	tip		0			ns
Shift clock fall to Latch pulse fall time	tsL		65			ns
Latch pulse rise to Shift clock rise time	tis		65			ns
Latch pulse fall to Shift clock fall time	t _{LH}		· 65			ns
Enable setup time	ts		45			ns
DISPOFF "L" pulse width	twoL		1.2			μs
DISPOFF removal time	trem		100			ns
Input signal rise time	t r	Note			50	ns
Input signal fall time	t:	1			50	ns
Output delay time (1) XCK to EIO ₁ ,EIO ₂	t _D	C _L =15 pF			95	ns
Output delay time (2) FR to Y ₁ -Y ₈₀	tpd ₁]			1.2	μs
Output delay time (3) LP to Y ₁ -Y ₈₀	tpd ₂] [1.2	μs
Output delay time (4) $\overline{\text{DISPOFF}}$ to $Y_1 - Y_{80}$	tpd3				1.2	μs

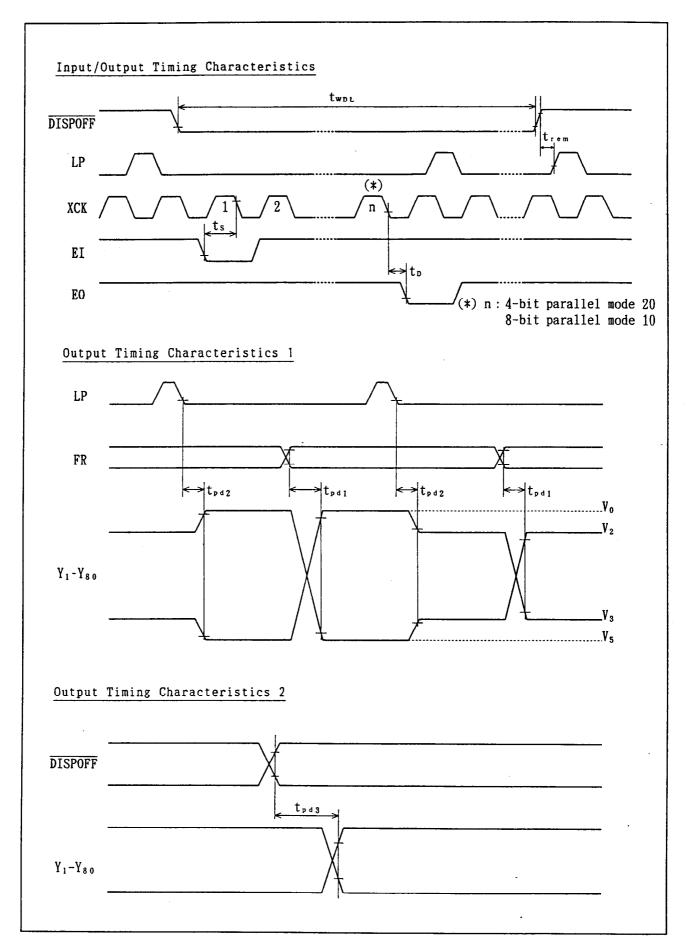
[Note] $(t_{CK}-t_{WCKH}-t_{WCKL})/2$ is maximum in the case of high speed operation.

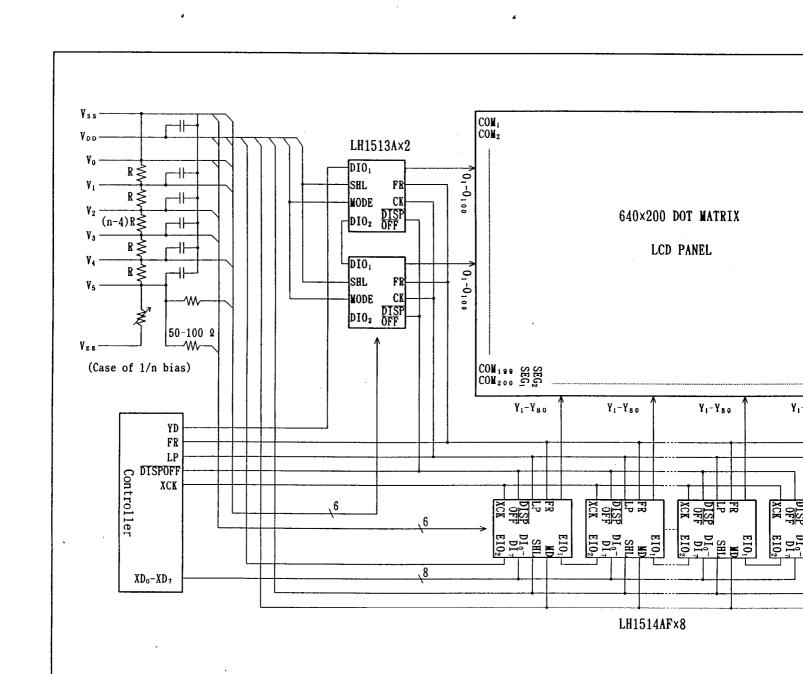
11-3. Timing Diagrams

Input Timing Characteristics











13. Example of Typical Characteristic

Parameter	Conditions	Mim.	Typ.	Max.	Unit
Typical Fundamental Rating	$Ta=+25 \text{ C}, V_{SS}=0 \text{ V}, V_{DD}=-5.0 \text{ V}$		50		ns
Propagation Delay Time					

14. PACKAGE AND PACKING SPECIFICATION

1. Package Outline Specification

Refer to drawing No. SPN2171-00

2. Markings

The meanings of the device code printed on each tape carrier package are as follows.

(1) Date code (example) : $\frac{4}{a}$ $\frac{3}{b}$ $\frac{7}{c}$ $\frac{0}{c}$

- a) denotes the last figure of Anno Domini (of production)
- b) denotes the week (of production)
- c) denotes the number of times of alteration

3. Packing Specifications

(1) Packing Materials

Item	Material	Purpose
Reel	Anti-static treated plastic (405mm dia.)	Packing of tape carrier package.
Separator	Anti-static treated PET (188 \(\alpha \) mt)	Protects device and prevents ESD (Electro Static Discharge)
Laminated aluminium bag	$(520 \times 600 \text{mm})$	Keeping dry.
Adhesive tape paper		Fixing of tape carrier package and sparator.
Carton	Cardboard(420x420x50mm)	Contains a reel.
Label	Paper	Indicates production name, lot.No., and quantity.
Desiccant	Silica gel	Drying of device

(2) Packing Form

- a) Tape carrier package(TCP) is wound on a reel with separators 1 and 2 and the ends of them are fixed with adhesive tape.
- b) A label indicating production name, lot no, and quantity is stuck on one side of the reel.
- c) The reel and silica gel is put in a laminated aluminium bag. Nitrogen gas is enclosed in the bag and the bag is sealed. The same label(b) is affixed to the bag. The bag is put in a carton and the same label(b) is affixed to one side of the carton.

* Specification of label

ТҮРЕ	
	PRODUCTION NAME LOT NO.
QUANTITY	QUANTITY
LOT(DATE)	SHIPPING DATE

4. Miscellaneous

- (1) The length of the tape carrier is $34 \sim 46$ meters maximum per reel, and depends on shipping quantity.
- (2) Before unpacking, prepare a work bench equipped with anti-static devices. Also, the operater should ware anti-static wrist bands.
- (3) The device, once unpacked, should be stored in a nitrogen gas, room temperature atomosphere and used within I week.

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